Singapore (23-26 November 2025)

IETEC Series

The International Engineering, Technology, Business and Health Education Conference (IETBHEC'25) is modified and reconfigured from International Engineering and Technology Education Conference (IETEC), a series of conferences initiated and coordinated by a team of higher education experts from around the globe, which has now transformed to an open, collegial and supportive working group (http://ietec.apaqa.org/). The inaugural IETEC (IETEC'11) was organised and staged at Taylor's University, Kuala Lumpur, Malaysia in January 2011 and after that IETEC was staged alternate years in Ho Chi Minh City, Vietnam; Sibiu, Romania; and Hanoi, Vietnam with collaboration among several Australia, European, Malaysian, Vietnamese and Indian universities and industry partners.

IETBHEC'25

IETBHEC'25 is the fifth conference in the IETEC series and will be held in vibrant, beautiful Singapore, between XX-XX November 2025. IETBHEC'25 will provide opportunities for engineering, technology and business education stakeholders from around the globe to explore the education outcomes, issues, and strategies needed to meet todays and tomorrow's challenges.

IETBHEC'25 will be hosted at Curtin University Singapore and is supported by San Jose State University, USA; Dr Homi Bhabha State Technical University Mumbai, India; Ho Chi Minh City University of Technology and Education, Vietnam (HCMUTE); and Universiti Teknology Malaysia (UTM).

The IETBHEC'25 will feature significant keynote addresses, plenary presentation sessions, interactive workshops, panel discussions, exhibition stalls, and opportunities for international collaborations.

Sponsorship and Exhibition

Corporate Sponsor	SGD 10,000
Platinum Sponsor	SGD 8,000
Gold Sponsor	SGD 5,000
Silver Sponsor	SGD 3,000
Banquet/Dinner Sponsor	SGD 4,000
Exhibition Booth	SGD 2,000

The IETBHEC'25 sponsorship can also be "unrestricted" contributions and/or "in-kind" such as printing of conference materials, morning and afternoon tea breaks, lunches and dinners, transportation, or any other direct expenses related to the conference organisation.

_	_		_		
\boldsymbol{c}	nt	2	ct	C	•

XXX

Sponsorship Benefits

CORPORATE

Sponsor PAGE (FULL PAGE COLOUR in Proceedings) SGD 10,000

CORPORATE SPONSOR BENEFITS:

- 1. Official announcement as the Corporate Sponsor.
- 2. Logo prominently displayed on all IETBHEC'25 Banners and Website.
- 3. Embossed company logo on IETBHEC'25 Bag and/or Folder.
- 4. Organisation logo to be affixed on the following back drops:
 - Official Opening Ceremony (non-exclusive)
 - Official Closing Ceremony (non-exclusive)
- 5. Organisation Logo, Summary of Products and Services printed in IETBHEC'25 Program Booklet and Conference Proceedings.
- 6. Invitation to the Opening and Closing ceremony.
- 7. Certificate of Appreciation.
- 8. Free IETBHEC'25 Conference kit (4).
- 9. One free exhibition booth space.
- 10. Receipt of Payment for Sponsorship (for Tax Purpose).
- 11. Announcement as a Corporate Sponsor in speeches during opening and closing ceremony.
- 12. A free table (5 seats) to the Conference Gala Banquet.

PLATINUM

Minimum of SGD 8,000

PLATINUM SPONSOR BENEFITS:

- 1. Logo prominently displayed on IETBHEC'25 website.
- 2. Logo displayed at breakout sessions during the IETBHEC'25 period.
- 3. Organisation Logo, Summary of Products and Services printed in Conference Program Booklet and Conference Proceedings.
- 4. Invitation to the Opening and Closing ceremony.
- 5. Certificate of Appreciation.
- 6. Free Conference kit (2).
- 7. Receipt of Payment for Sponsorship (Tax Purpose).
- 8. Free seats to the Conference Gala Banquet (3).

GOLD Minimum of SGD 5,000

GOLD SPONSOR BENEFITS:

- 1. Logo displayed at Breakout sessions during the IETBHEC'25 period.
- 2. Organization Logo, Summary of Products and Services printed in Conference Program Booklet and Conference Proceedings.
- 3. Invitation to the Opening and Closing Ceremony.
- 4. Certificate of Appreciation.
- 5. Free Conference kit (2).
- 6. Receipt of Payment for Sponsorship (Tax Purpose).
- 7. Free seats to the Conference Gala Banquet (2).

SILVER Minimum of SGD 3000

SILVER SPONSOR BENEFITS:

- 1. Organization Logo, Summary of Products and Services printed in Conference Program Booklet and Conference Proceedings.
- 2. Certificate of Appreciation.
- 3. Invitation to the Opening and Closing Ceremony.
- 4. Receipt of Payment for Sponsorship (Tax Purpose).
- 5. One free seat to the Conference Gala Banquet.

BANQUET (DINNER) SPONSOR Minimum of SGD 4,000

BANQUET (DINNER) SPONSOR BENEFITS:

- 1. Logo prominently displayed.
- 2. Logo displayed at Banquet room during dinner.
- 3. Organization Logo, Summary of Products and Services printed in Conference Program Booklet and Conference Proceedings.
- 4. A free table (5 seats) to the Conference Gala Banquet.
- 5. Certificate of Appreciation.
- 6. Invitation to the Opening and Closing Ceremony.
- 7. Receipt of Payment for Sponsorship (Tax Purpose).

EXHIBITION BOOTH

Minimum of SGD 2,000

The IETBHEC'25 provides excellent opportunities to take part in the Conference Exhibition to ensure maximum exposure to the academic and industry stakeholders in engineering, technology and business education. Exhibiting at the IETBHEC'25 Conference will provide your organisation with access to conference delegates from all around the globe.

EXHIBITION BOOTH RATE BENEFITS:

- 1. Includes exhibition booth (3mX3m) for the duration of conference.
- 2. Exhibition signage.
- 3. Information counter.
- 4. 2 folding chairs.
- 5. 5 sets of vinyl sticker cut-out for booth fascia name.
- 6. Adequate lighting and power supply.
- 7. Invitation to the Opening and Closing Ceremony.
- 8. One Complimentary registration (Includes: one free seat to the Conference Gala Banquet).

The IETBHEC'25 sponsorship" can also be "unrestricted" contributions and/or "in-kind" such as printing of conference materials, morning and afternoon tea breaks, lunches and dinners, transportation, or any other direct expenses related to the conference. Please contact us to discuss this further.

Conference Website: www.ietec.apaqa.org/